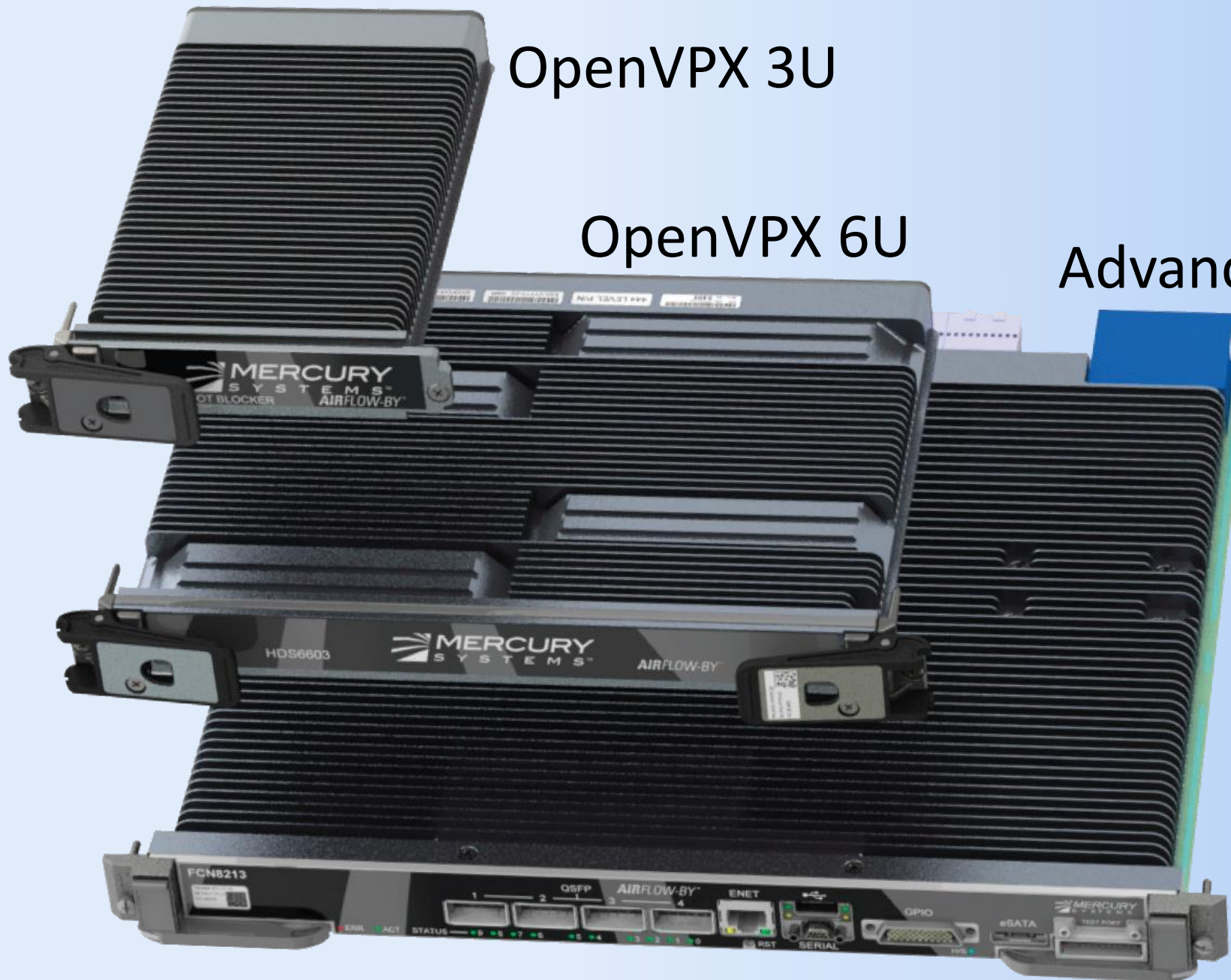


# Mercury Standard Form Factor

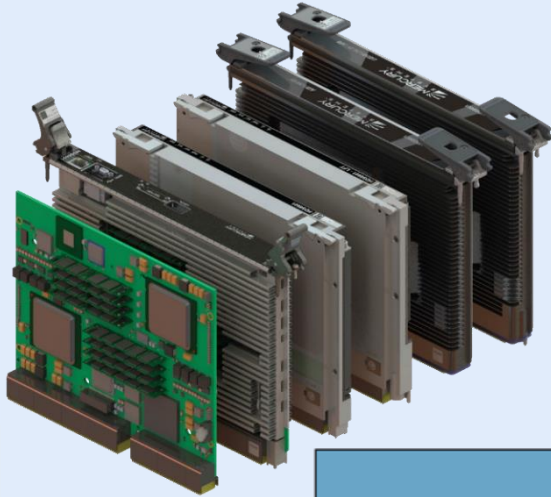
OpenVPX 3U

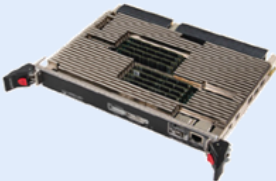
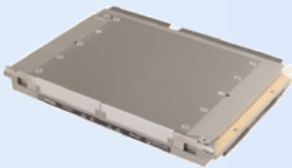
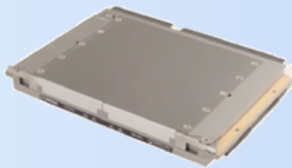
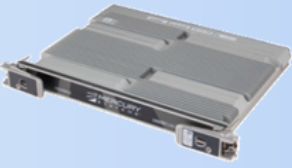

OpenVPX 6U

AdvancedTCA



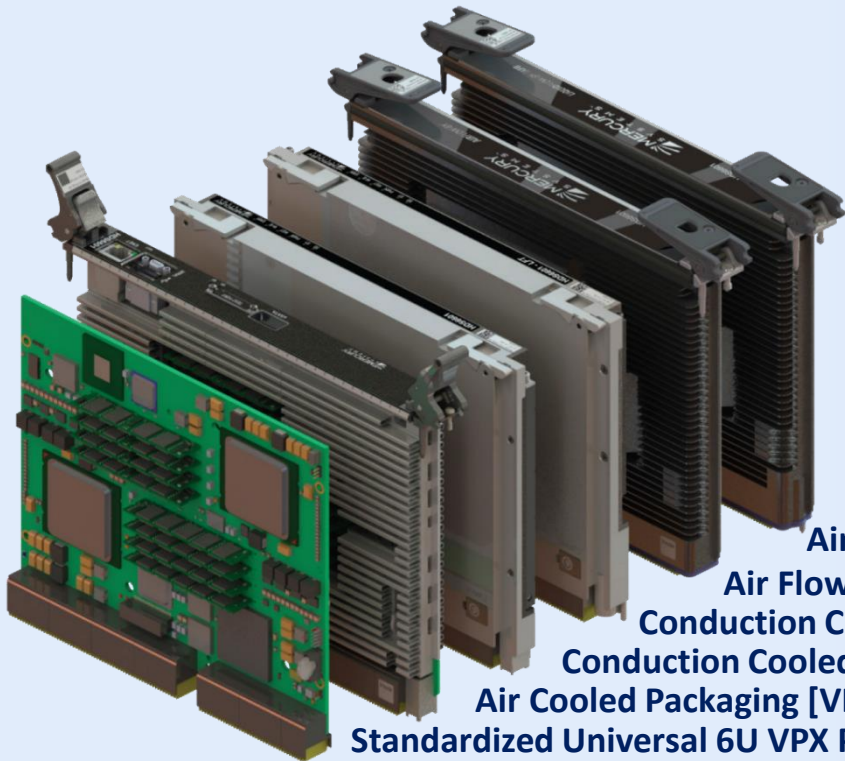
# Mercury Standard Cooling Method



	Cooling Technology				
	Air-Cooled	Conduction-Cooled	Liquid Flow-Thru	Air Flow-By	Liquid Flow-By
					
	Most cost effective packaging solution.	Robust module packaging that dissipates module heat to the chassis.	For rugged liquid cooling.	Most efficient OpenVPX air-cooling technology available – Modules are sealed removing the need for filtration.	The current state-of-the-art in cooling technology – A harmonized Air Flow-By and Liquid-Cooled solution.
Cooling Capacity	110 Watts	140 Watts	300+ Watts	250 Watts	300+ Watts
Ruggedness Level	Commercial	Most rugged	Most rugged	Very rugged	Very rugged
Environmental Protection	Fair	Good	Good	Best	Best
Cooling Fluid	Air	Conduction from OpenVPX modules to chassis	Liquid and conduction	Air	Air/liquid redundant/dual
Cooling	Single-sided	Double-sided	Double-sided	Double-sided	Double-sided
Pitch	1.0"	1.0"	1.0"	1.0"	1.0"
Typical Application	Lab development and data room deployments	Rugged, sealed compute applications	Rugged, sealed compute applications	High power and "dirty-air" applications	High power/altitude applications – Modules can also air cool themselves without coolant



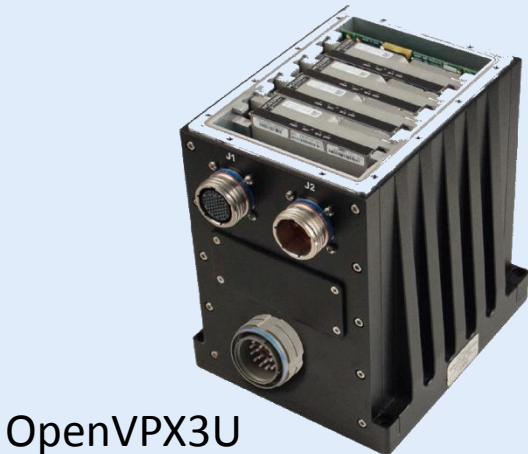
# Mercury Standard Cooling Chassis Method



- Air Flow By Packaging w/LFB [VITA 48.X]
- Air Flow By Packaging [VITA 48.7]
- Conduction Cooled Packaging w/LFT [VITA 48.X]
- Conduction Cooled Packaging [VITA 48.2]
- Air Cooled Packaging [VITA 48.1]
- Standardized Universal 6U VPX PCBA



Air Cool  
VITA48.1



OpenVPX3U  
Conduction Cool VITA48.2  
Safety Mission Computer



**AIRFLOW-BY™**  
VITA48.7

Conduction Cool w/LFT  
VITA48.2